

74LCX244

Low Voltage Buffer/Line Driver with 5V Tolerant Inputs and Outputs

General Description

The LCX244 contains eight non-inverting buffers with 3-STATE outputs. The device may be employed as a memory address driver, clock driver and bus-oriented transmitter/receiver. The LCX244 is designed for low voltage (2.5V or 3.3V) V_{CC} applications with capability of interfacing to a 5V signal environment.

The LCX244 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

Features

- 5V tolerant inputs and outputs
- 2.3V–3.6V V_{CC} specifications provided
- 6.5 ns t_{PD} max ($V_{CC} = 3.3V$), 10 μA I_{CC} max
- Power down high impedance inputs and outputs
- Supports live insertion/withdrawal (Note 1)
- ± 24 mA output drive ($V_{CC} = 3.0V$)
- Implements patented noise/EMI reduction circuitry
- Latch-up performance exceeds 500 mA
- ESD performance:
 - Human body model > 2000V
 - Machine model > 200V

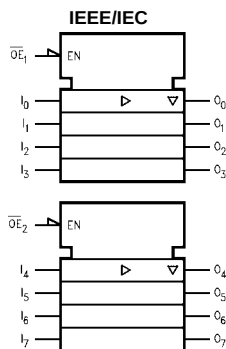
Note 1: To ensure the high-impedance state during power up or down, $\overline{OE}$ should be tied to V_{CC} through a pull-up resistor: the minimum value or the resistor is determined by the current-sourcing capability of the driver.

Ordering Code:

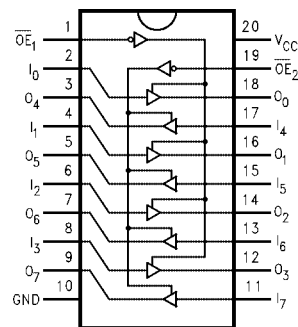
Order Number	Package Number	Package Description
74LCX244WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74LCX244SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74LCX244MSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
74LCX244MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbol



Connection Diagram



Pin Descriptions

Pin Names	Description
$\overline{OE}_1, \overline{OE}_2$	3-STATE Output Enable Inputs
I_0-I_7	Inputs
O_0-O_7	Outputs

Truth Tables

Inputs		Outputs (Pins 12, 14, 16, 18)
$\overline{OE}_1$	I_n	
L	L	L
L	H	H
H	X	Z

Inputs		Outputs (Pins 3, 5, 7, 9)
$\overline{OE}_2$	I_n	
L	L	L
L	H	H
H	X	Z

H = HIGH Voltage Level
 L = LOW Voltage Level
 X = Immaterial
 Z = High Impedance

Absolute Maximum Ratings ^(Note 2)				
Symbol	Parameter	Value	Conditions	Units
V _{CC}	Supply Voltage	−0.5 to +7.0		V
V _I	DC Input Voltage	−0.5 to +7.0		V
V _O	DC Output Voltage	−0.5 to +7.0 −0.5 to V _{CC} + 0.5	Output in 3-STATE Output in HIGH or LOW State (Note 3)	V
I _{IK}	DC Input Diode Current	−50	V _I < GND	mA
I _{OK}	DC Output Diode Current	−50 +50	V _O < GND V _O > V _{CC}	mA
I _O	DC Output Source/Sink Current	±50		mA
I _{CC}	DC Supply Current per Supply Pin	±100		mA
I _{GND}	DC Ground Current per Ground Pin	±100		mA
T _{STG}	Storage Temperature	−65 to +150		°C

Recommended Operating Conditions (Note 4)				
Symbol	Parameter	Min	Max	Units
V _{CC}	Supply Voltage	Operating Data Retention	2.0 1.5	3.6 3.6 V
V _I	Input Voltage	0	5.5	V
V _O	Output Voltage	HIGH or LOW State 3-STATE	0 0	V _{CC} 5.5 V
I _{OH} /I _{OL}	Output Current	V _{CC} = 3.0V–3.6V V _{CC} = 2.7V–3.0V V _{CC} = 2.3V–2.7V		±24 ±12 ±8 mA
T _A	Free-Air Operating Temperature	−40	85	°C
Δt/ΔV	Input Edge Rate, V _{IN} = 0.8V–2.0V, V _{CC} = 3.0V	0	10	ns/V

Note 2: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The “Recommended Operating Conditions” table will define the conditions for actual device operation.

Note 3: I_O Absolute Maximum Rating must be observed.

Note 4: Unused inputs or I/Os must be held HIGH or LOW. They may not float.

DC Electrical Characteristics						
Symbol	Parameter	Conditions	V _{CC} (V)	T _A = −40°C to +85°C		Units
				Min	Max	
V _{IH}	HIGH Level Input Voltage		2.3 – 2.7 2.7 – 3.6	1.7 2.0		V
V _{IL}	LOW Level Input Voltage		2.3 – 2.7 2.7 – 3.6		0.7 0.8	V
V _{OH}	HIGH Level Output Voltage	I _{OH} = −100 μA I _{OH} = −8 mA I _{OH} = −12 mA I _{OH} = −18 mA I _{OH} = −24 mA	2.3 – 3.6 2.3 2.7 3.0 3.0	V _{CC} − 0.2 1.8 2.2 2.4 2.2		V
V _{OL}	LOW Level Output Voltage	I _{OL} = 100 μA I _{OL} = 8 mA I _{OL} = 12 mA I _{OL} = 16 mA I _{OL} = 24 mA	2.3 – 3.6 2.3 2.7 3.0 3.0		0.2 0.6 0.4 0.4 0.55	V
I _I	Input Leakage Current	0 ≤ V _I ≤ 5.5V	2.3 – 3.6		±5.0	μA
I _{OZ}	3-STATE Output Leakage	0 ≤ V _O ≤ 5.5V V _I = V _{IH} or V _{IL}	2.3 – 3.6		±5.0	μA
I _{OFF}	Power-Off Leakage Current	V _I or V _O = 5.5V	0		10	μA

DC Electrical Characteristics (Continued)

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = -40°C to +85°C		Units
				Min	Max	
I _{CC}	Quiescent Supply Current	V _I = V _{CC} or GND	2.3 – 3.6		10	μA
		3.6V ≤ V _I , V _O ≤ 5.5V (Note 5)	2.3 – 3.6		±10	
ΔI _{CC}	Increase in I _{CC} per Input	V _{IH} = V _{CC} - 0.6V	2.3 – 3.6		500	μA

Note 5: Outputs disabled or 3-STATE only.

AC Electrical Characteristics

Symbol	Parameter	T _A = -40°C to +85°C, R _L = 500Ω						Units
		V _{CC} = 3.3V ± 0.3V		V _{CC} = 2.7V		V _{CC} = 2.5V ± 0.2		
		C _L = 50 pF		C _L = 50 pF		C _L = 30 pF		
		Min	Max	Min	Max	Min	Max	
t _{PHL}	Propagation Delay	1.5	6.5	1.5	7.5	1.5	7.8	ns
t _{PLH}	Data to Output	1.5	6.5	1.5	7.5	1.5	7.8	
t _{PZL}	Output Enable Time	1.5	8.0	1.5	9.0	1.5	10.0	ns
t _{PZH}		1.5	8.0	1.5	9.0	1.5	10.0	
t _{PLZ}	Output Disable Time	1.5	7.0	1.5	8.0	1.5	8.4	ns
t _{PHZ}		1.5	7.0	1.5	8.0	1.5	8.4	
t _{OSHL} t _{OSLH}	Output to Output Skew (Note 6)		1.0 1.0					ns

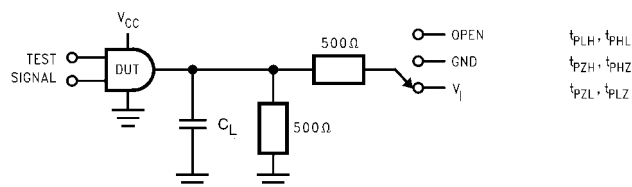
Note 6: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

Dynamic Switching Characteristics

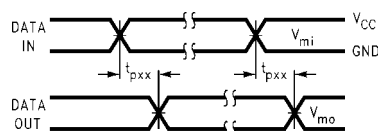
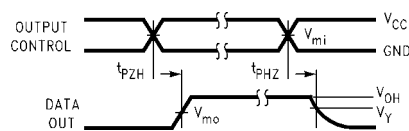
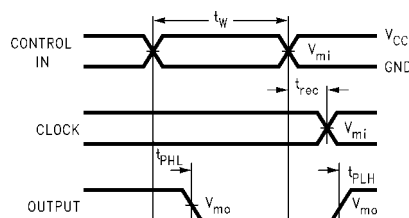
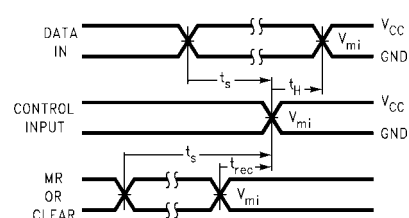
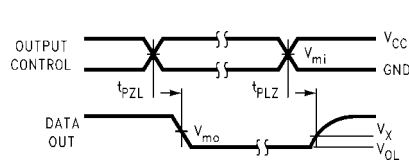
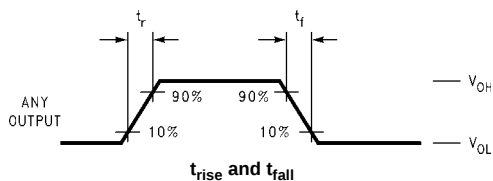
Symbol	Parameter	Conditions	V _{CC} (V)	T _A = 25°C	Units
				Typical	
V _{OLP}	Quiet Output Dynamic Peak V _{OL}	C _L = 50 pF, V _{IH} = 3.3V, V _{IL} = 0V C _L = 30 pF, V _{IH} = 2.5V, V _{IL} = 0V	3.3 2.5	0.8 0.6	V
V _{OLV}	Quiet Output Dynamic Valley V _{OL}	C _L = 50 pF, V _{IH} = 3.3V, V _{IL} = 0V C _L = 30 pF, V _{IH} = 2.5V, V _{IL} = 0V	3.3 2.5	-0.8 -0.6	V

Capacitance

Symbol	Parameter	Conditions	Typical	Units
C _{IN}	Input Capacitance	V _{CC} = Open, V _I = 0V or V _{CC}	7	pF
C _{OUT}	Output Capacitance	V _{CC} = 3.3V, V _I = 0V or V _{CC}	8	pF
C _{PD}	Power Dissipation Capacitance	V _{CC} = 3.3V, V _I = 0V or V _{CC} , f = 10 MHz	25	pF

AC LOADING and WAVEFORMS Generic for LCX Family**FIGURE 1. AC Test Circuit (C_L includes probe and jig capacitance)**

Test	Switch
t_{PLH} , t_{PHL}	Open
t_{PZL} , t_{PLZ}	6V at $V_{CC} = 3.3 \pm 0.3V$ $V_{CC} \times 2$ at $V_{CC} = 2.5 \pm 0.2V$
t_{PZH} , t_{PHZ}	GND

**Waveform for Inverting and Non-Inverting Functions****3-STATE Output High Enable and Disable Times for Logic****Propagation Delay, Pulse Width and t_{rec} Waveforms****Setup Time, Hold Time and Recovery Time for Logic****3-STATE Output Low Enable and Disable Times for Logic****FIGURE 2. Waveforms**
(Input Characteristics; $f = 1\text{MHz}$, $t_r = t_f = 3\text{ns}$)

Symbol	V_{CC}		
	$3.3V \pm 0.3V$	$2.7V$	$2.5V \pm 0.2V$
V_{mi}	1.5V	1.5V	$V_{CC}/2$
V_{mo}	1.5V	1.5V	$V_{CC}/2$
V_x	$V_{OL} + 0.3V$	$V_{OL} + 0.3V$	$V_{OL} + 0.15V$
V_y	$V_{OH} - 0.3V$	$V_{OH} - 0.3V$	$V_{OH} - 0.15V$

Schematic Diagram Generic for LCX Family

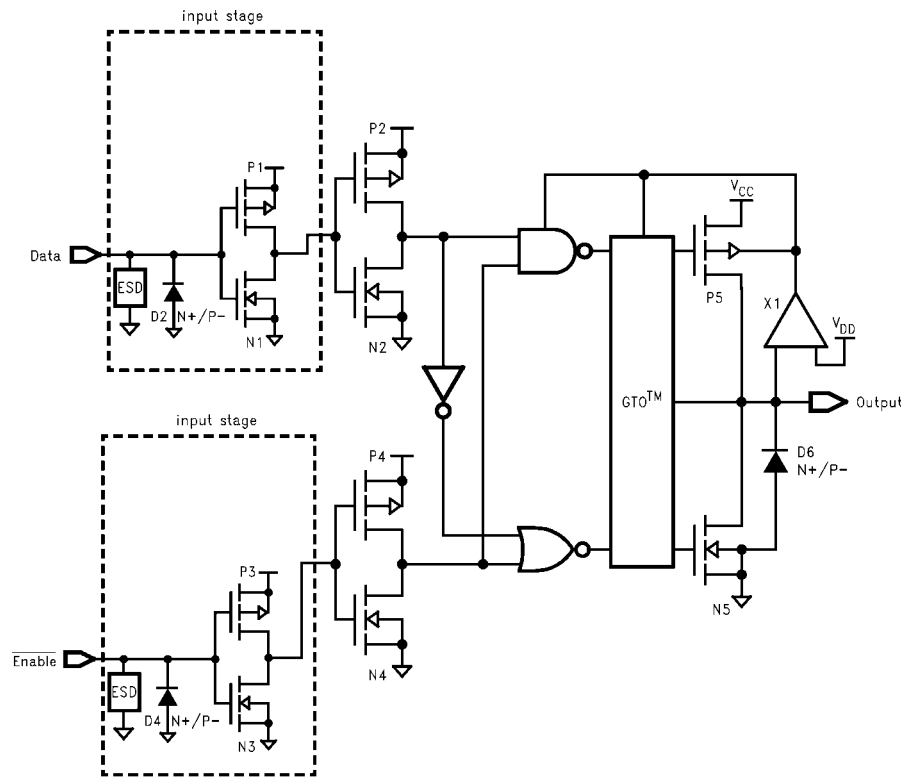
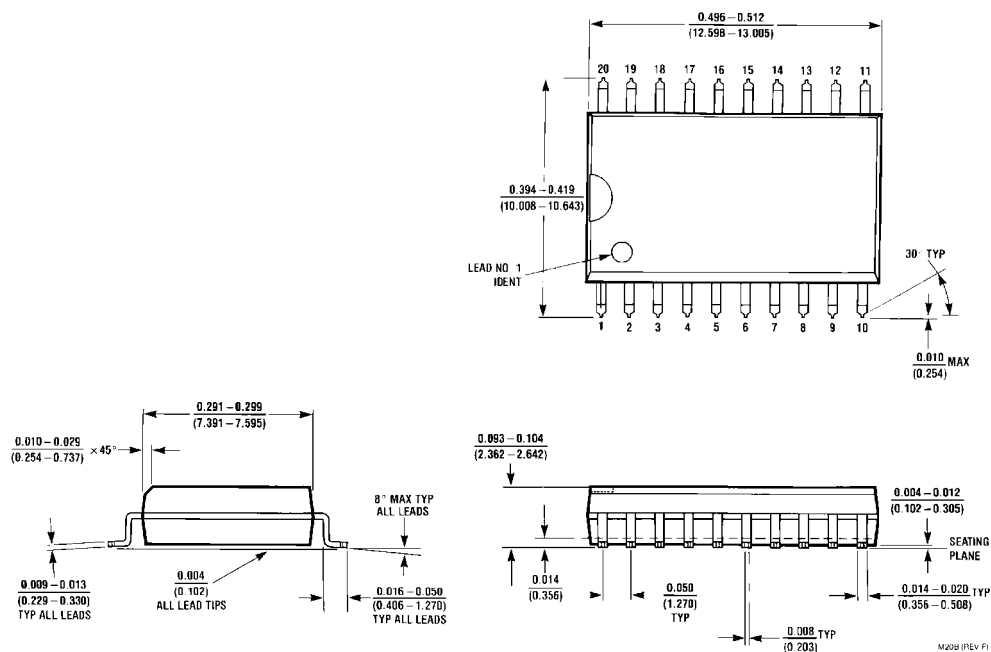


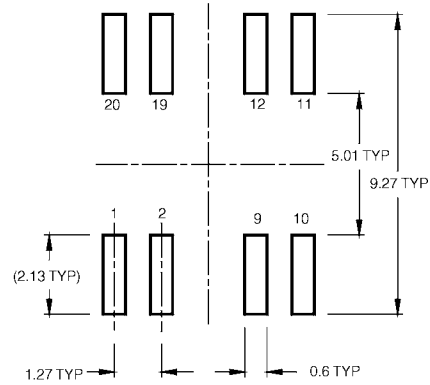
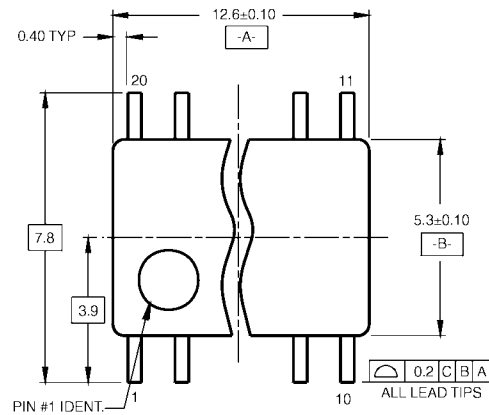
FIGURE 3.

Physical Dimensions inches (millimeters) unless otherwise noted

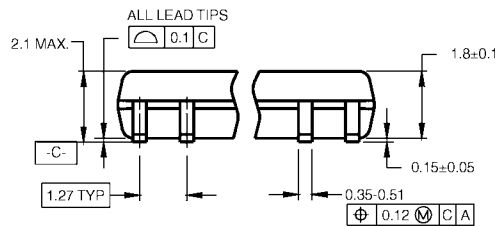


**20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
Package Number M20B**

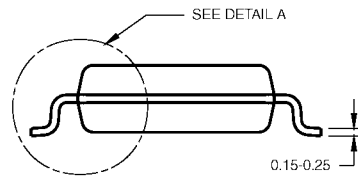
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



LAND PATTERN RECOMMENDATION



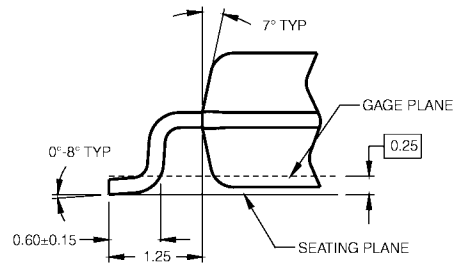
DIMENSIONS ARE IN MILLIMETERS



NOTES:

- CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
- DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

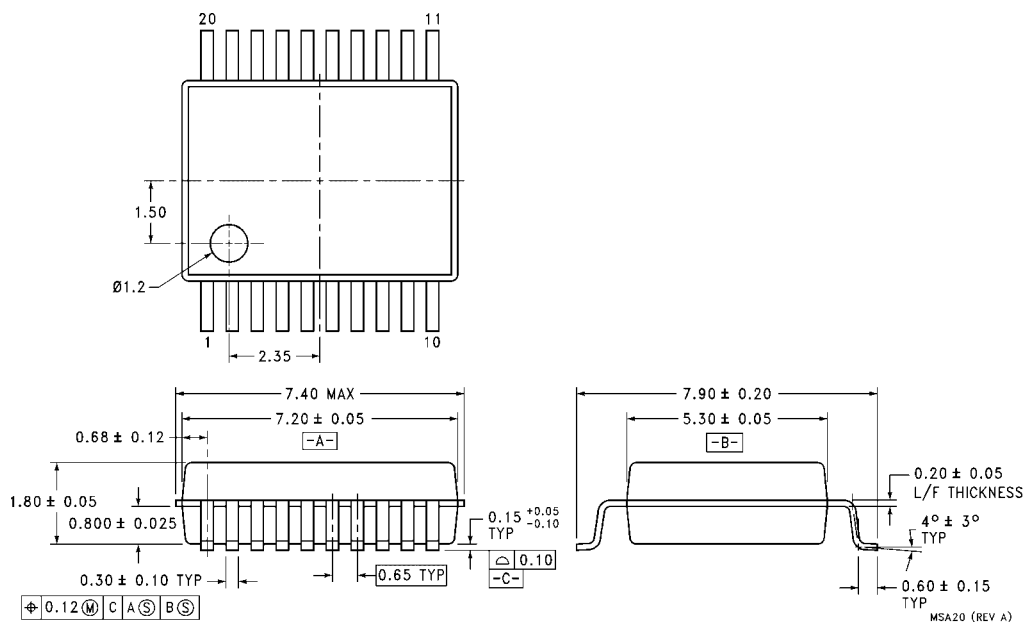
M20DRevB1



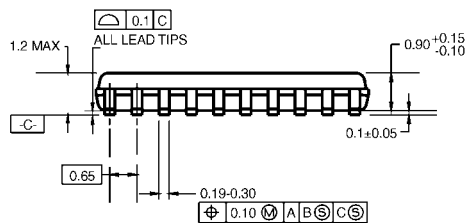
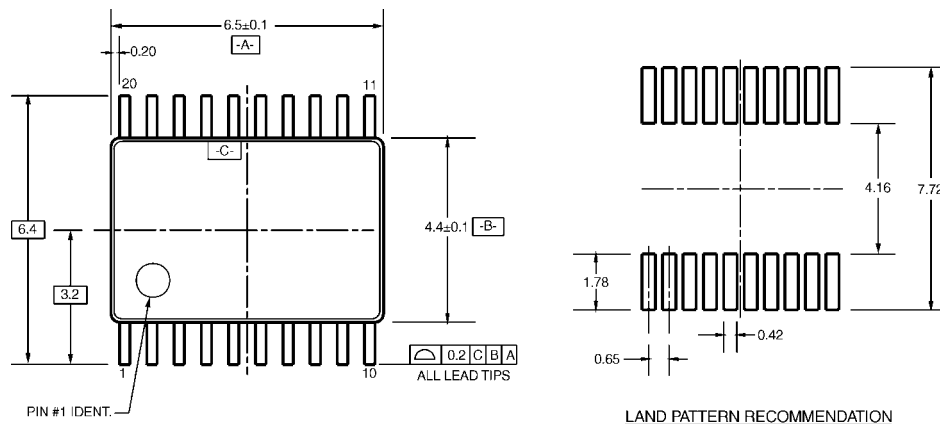
DETAIL A

**20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M20D**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



**20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
Package Number MSA20**

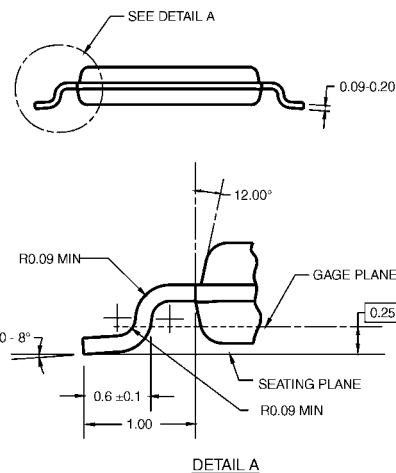
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE 7/93.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC20RevD1



**20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC20**

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